

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t6650hs5#trmpbf

(Engineering Calculation)

TSOT-23

(printed on: 2020-07-11 20:41:24)

TOTAL MASS (g) : 0.012481

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.000567 | 1000000 | 45428.1992188 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.004485 | 975000 | 359339.4375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000110 | 24000 | 8813.23046875 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000001 | 300 | 80.1202774048 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000003 | 700 | 240.360839844 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.004599 | 1000000 | 368473.15625 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000635 | 1000000 | 50895.2578125 | | |
| | | External Plating Total: | | | | 0.000635 | 1000000 | 50895.2578125 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000080 | 1000000 | 6409.62158203 | | |
| Internal Plating Total: | | | | 0.000080 | 1000000 | 6409.62158203 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000409 | 750000 | 32769.1914062 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000136 | 250000 | 10896.3574219 | | |
| Die Attach Total: | | | | 0.000545 | 1000000 | 43665.5507812 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.000775 | 130000 | 62093.21875 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.004947 | 830000 | 396355.03125 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000209 | 35000 | 16745.1386719 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000030 | 5000 | 2403.60839844 | | |
| | | Encapsulation Total: | | | | 0.005961 | 1000000 | 477596.96875 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000094 | 1000000 | 7531.30615234 | | |
| | | | | | TOTAL MASS (g) : | 0.012481 | | |